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(12) **United States Design Patent**  
**Sako et al.**

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(45) **Date of Patent:** **\*\* Apr. 15, 2003**

(54) **PORTION OF SEMICONDUCTOR DEVICE**

JP

1079850

7/2000

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**OTHER PUBLICATIONS**

Extract of Denpa Shimbun (newspaper) showing a PAM built-in microcomputer (MB91110).

Extract of Denpa Shimbun (newspaper) showing a CCD signal processor (VSP2101).

Extract of Denpa Shimbun (newspaper) showing a AV decoder system LSI (MN677521) for a DVD player.

Extract of Denpa Shimbun (newspaper) showing a Scan USB (NET 1031).

Toshiba Catalog of micro controller (TMP86CM25F).

\* cited by examiner

(73) Assignee: **Kabushiki Kaisha Toshiba**, Tokyo (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/161,325**

(22) Filed: **May 29, 2002**

(30) **Foreign Application Priority Data**

Nov. 30, 2001 (JP) ..... 2001-035199

(51) **LOC (7) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Search** ..... D13/182; 174/52.1,  
174/52.2, 52.4, 52.5; 206/710, 719; 257/666,  
678, 690, 691-697, 704, 780; 361/600,  
742, 820

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Maier & Neustadt, P.C.

(57) **CLAIM**

The ornamental design for a portion of semiconductor device, as shown and described.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

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**FOREIGN PATENT DOCUMENTS**

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**DESCRIPTION**

FIG. 1 is a front, bottom and right side perspective view of a portion of semiconductor device, showing our new design;

FIG. 2 is a front elevational view thereof;

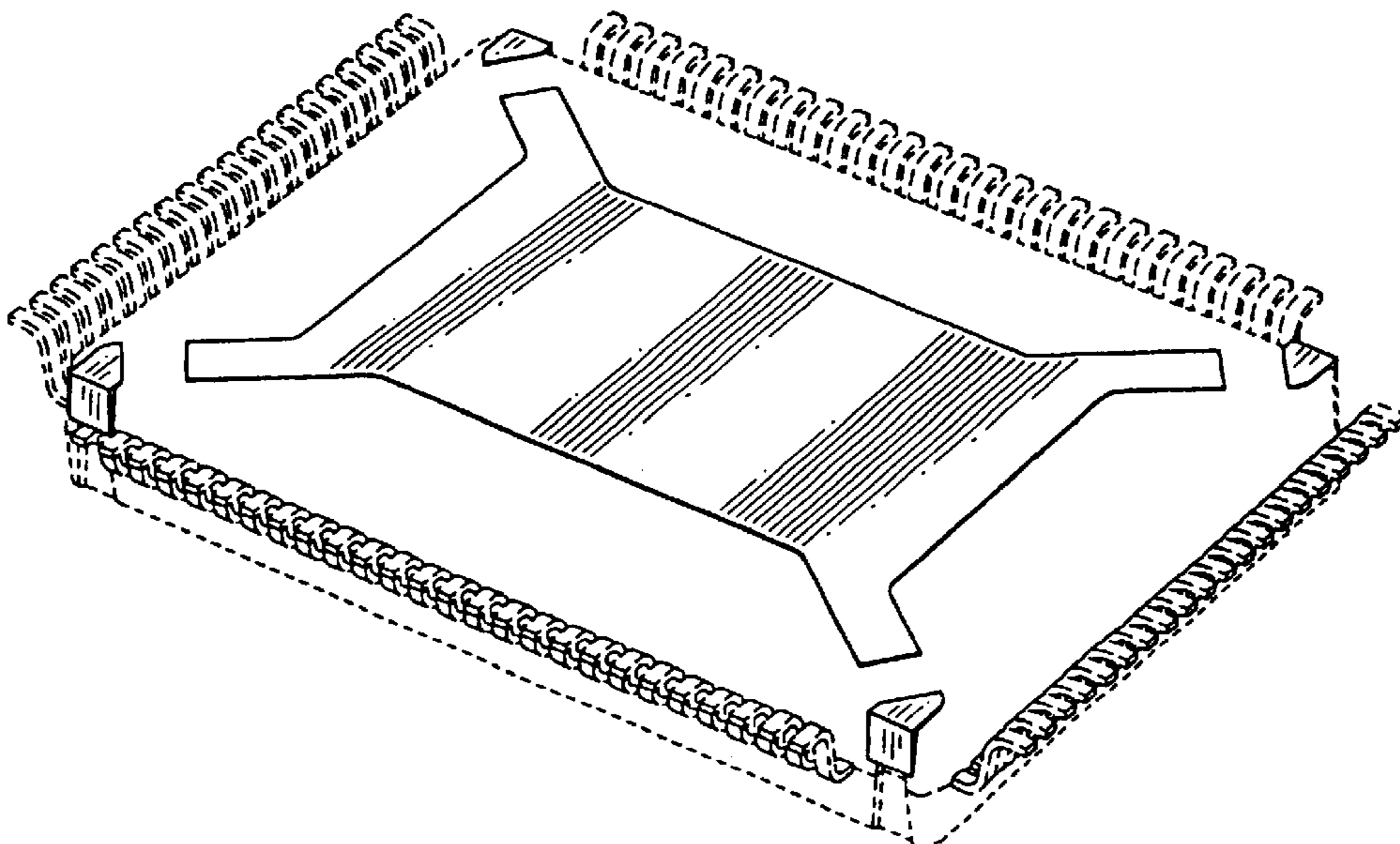
FIG. 3 is a top plan view thereof; a bottom plan view being a mirror image thereof;

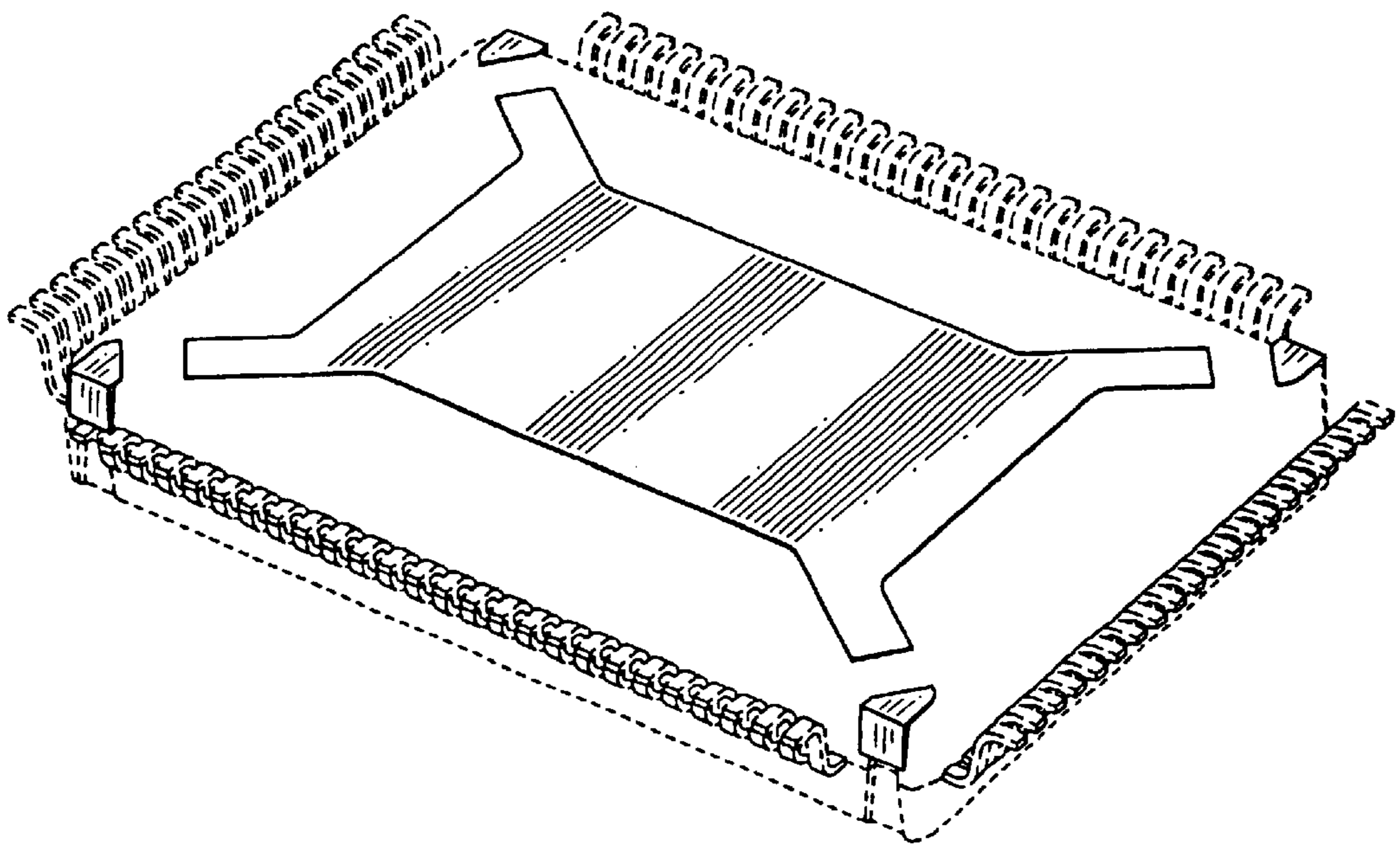
FIG. 4 is a right side elevational view thereof; a left side elevational view being a mirror image thereof; and,

FIG. 5 is a rear elevational view thereof.

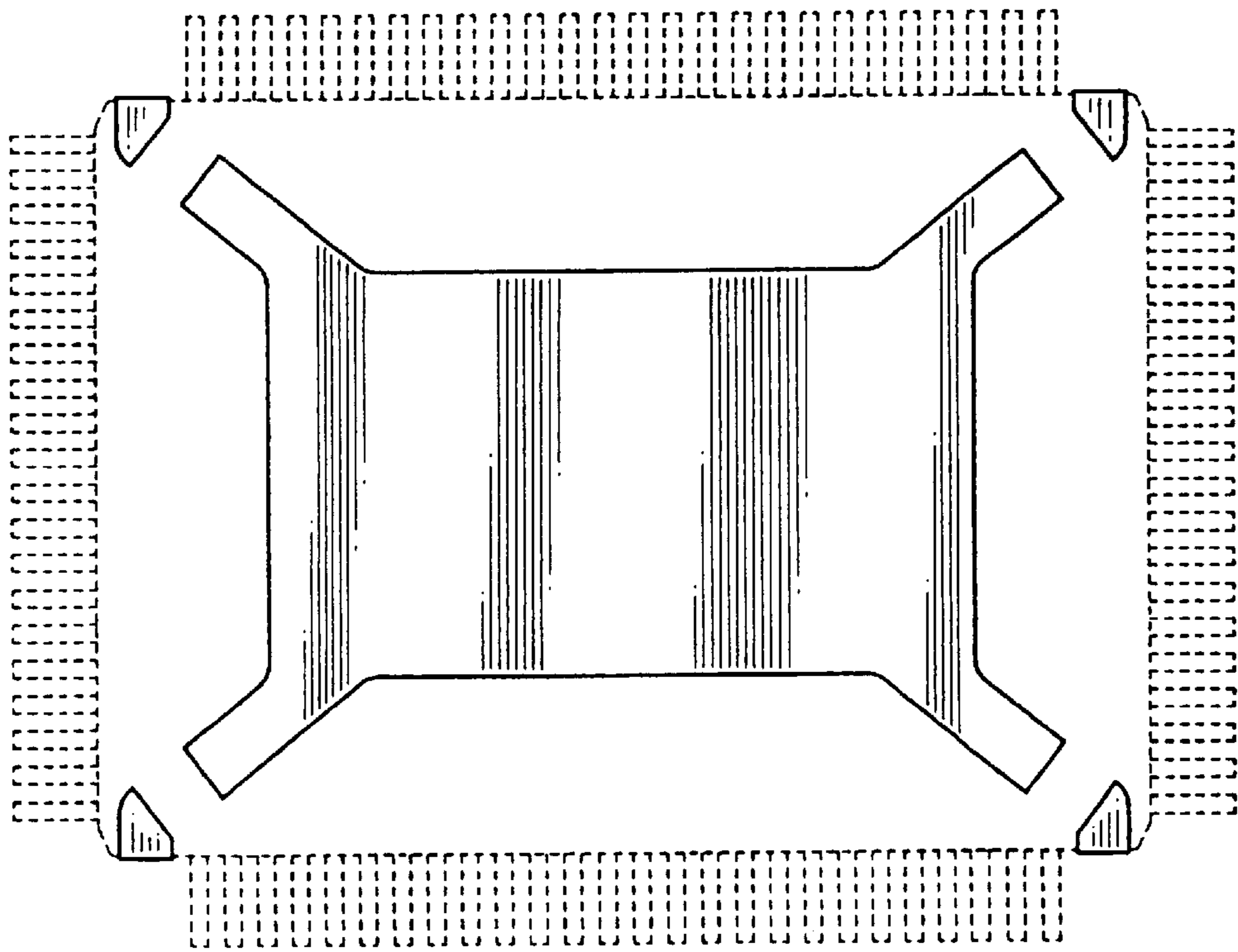
The broken line portions are shown for illustrative purpose only and form no part of the claimed design.

**1 Claim, 2 Drawing Sheets**

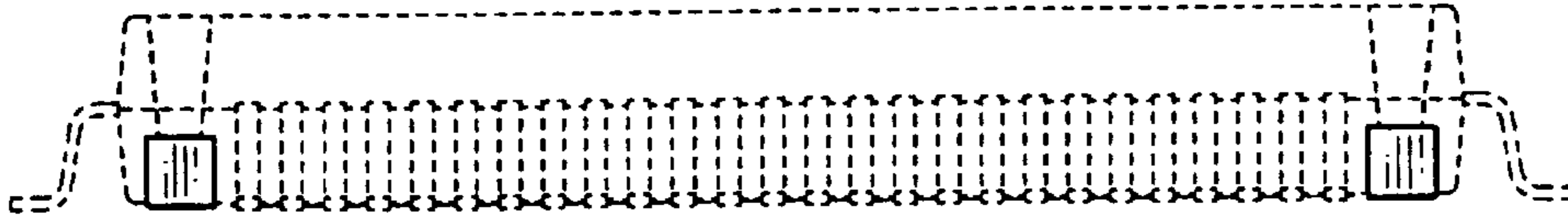




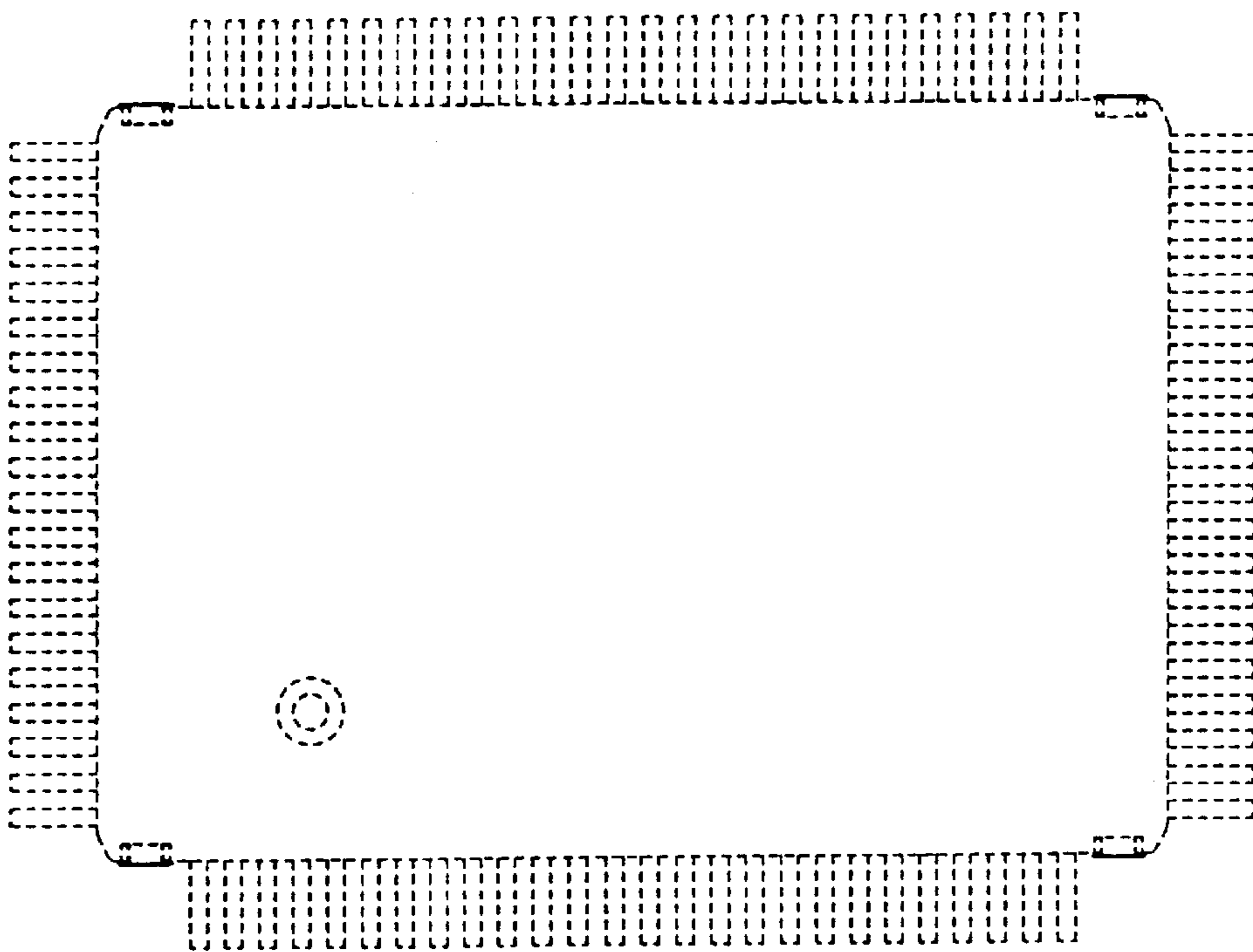
*Fig. 1*



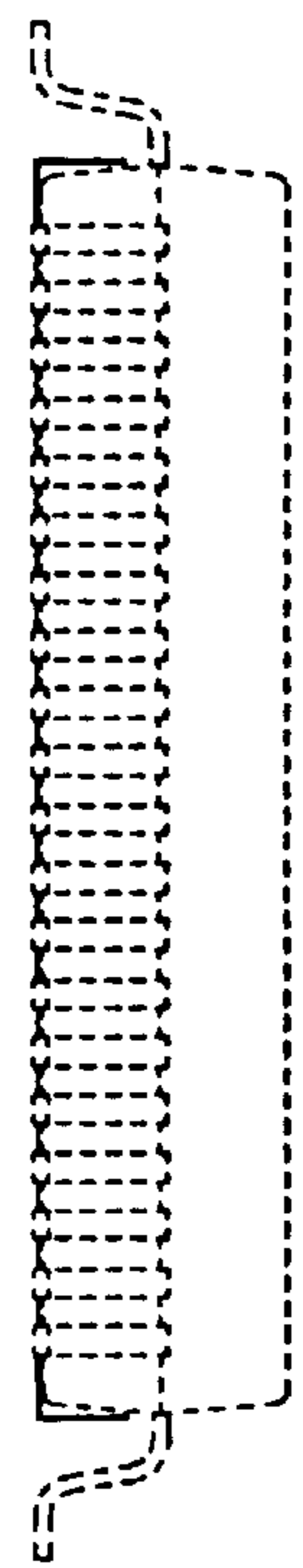
*Fig. 2*



*Fig. 3*



*Fig. 5*



*Fig. 4*